



浙江世菱半导体有限公司
ZHEJIANG SHILING SEMICONDUCTOR CO.,LTD.

产品规格书

Specification of products

产品名称：快恢复二极管

产品型号：MFDK200U6NK4

浙江世菱半导体有限公司
ZHEJIANG SHILING SEMICONDUCTOR CO., LTD.

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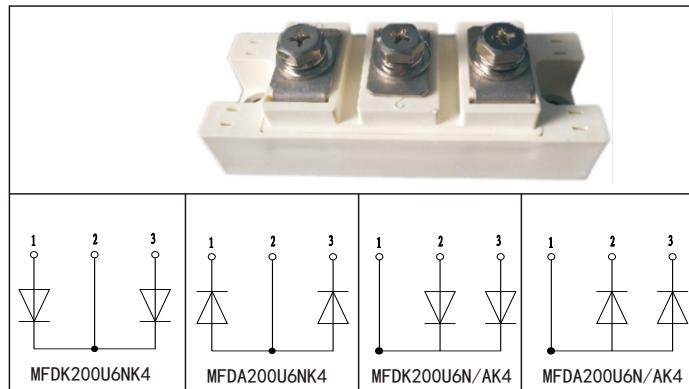
拟制	审核	核准
林益龙	曹剑龙	宗瑞

PRODUCT FEATURES

- ☒ Ultrafast Reverse Recovery Time
- ☒ Soft Reverse Recovery Characteristics
- ☒ Low Reverse Recovery Loss
- ☒ Low Forward Voltage
- ☒ High Surge Current Capability
- ☒ Low Inductance Package

APPLICATIONS

- ☒ Inversion Welder
- ☒ Uninterruptible Power Supply (UPS)
- ☒ Plating Power Supply
- ☒ Ultrasonic Cleaner and Welder
- ☒ Converter & Chopper
- ☒ Power Factor Correction (PFC) Circuit



ABSOLUTE MAXIMUM RATINGS

$T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V_R	Maximum D.C. Reverse Voltage		600	V
V_{RRM}	Maximum Repetitive Reverse Voltage		600	V
$I_{F(AV)}$	Average Forward Current	$T_c=110^\circ\text{C}$, Per Diode	100	A
		$T_c=110^\circ\text{C}$, Per Moudle	200	A
$I_{F(RMS)}$	RMS Forward Current	$T_c=110^\circ\text{C}$, Per Diode	280	A
I_{FSM}	Non-Repetitive Surge Forward Current	$T_J=45^\circ\text{C}$, $t=10\text{ms}$, 50Hz, Sine	2000	A
		$T_J=45^\circ\text{C}$, $t=8.3\text{ms}$, 60Hz, Sine	2200	A
I^2t	I^2t (For Fusing)	$T_J=45^\circ\text{C}$, $t=10\text{ms}$, 50Hz, Sine	20000	A^2s
		$T_J=45^\circ\text{C}$, $t=8.3\text{ms}$, 60Hz, Sine	24200	A^2s
P_D	Power Dissipation		694	W
T_J	Junction Temperature		-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-40 to +125	$^\circ\text{C}$
V_{isol}	Insulation Test Voltage	AC, $t=1\text{min}$	3000	V
Torque	Module-to-Sink	Recommended (M6)	3~5	N.M
Torque	Module Electrodes	Recommended (M6)	3~5	N.M
R_{eJC}	Thermal Resistance	Junction-to-Case	0.18	$^\circ\text{C }/\text{W}$
Weight			155	g

ELECTRICAL CHARACTERISTICS

$T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{RM}	Reverse Leakage Current	$V_R=600\text{V}$	--	--	1	mA
		$V_R=600\text{V}, T_J=125^\circ\text{C}$	--	--	5	mA
V_F	Forward Voltage	$I_F=200\text{A}$	--	1.15	1.60	V
		$I_F=200\text{A}, T_J=125^\circ\text{C}$	--	--	1.45	V
t_{rr}	Reverse Recovery Time	$I_F=1\text{A}, V_R=30\text{V}, di_F/dt=-200\text{A}/\mu\text{s}$	--	50	--	ns
t_{rr}	Reverse Recovery Time	$V_R=300\text{V}, I_F=200\text{A}$	--	140	--	ns
I_{RRM}	Max. Reverse Recovery Current	$di_F/dt=-200\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	--	16	--	A
t_{rr}	Reverse Recovery Time	$V_R=300\text{V}, I_F=200\text{A}$	--	232	--	ns
I_{RRM}	Max. Reverse Recovery Current	$di_F/dt=-200\text{A}/\mu\text{s}, T_J=125^\circ\text{C}$	--	26	--	A

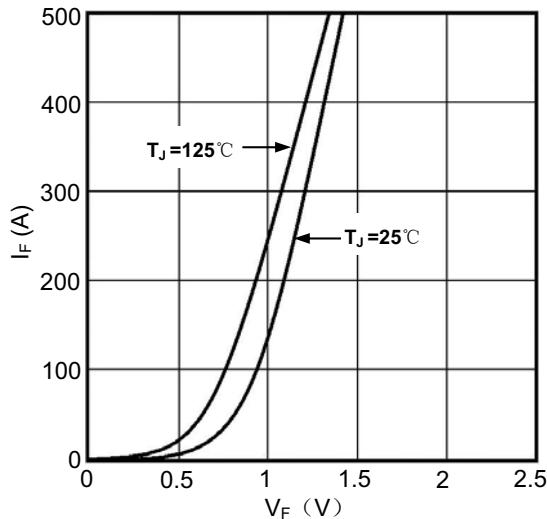


Figure 1. Forward Voltage Drop vs Forward Current

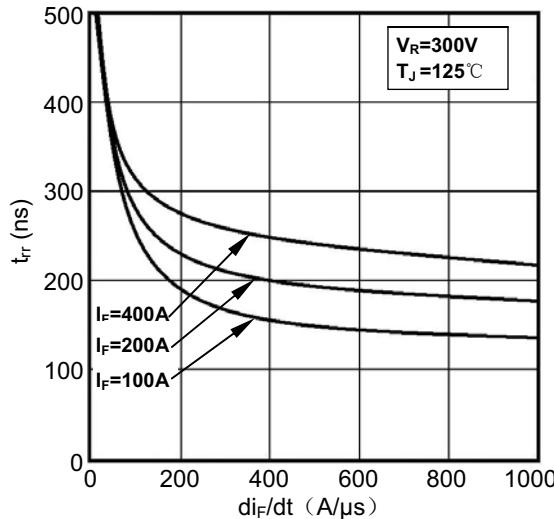


Figure 2. Reverse Recovery Time vs di_F/dt

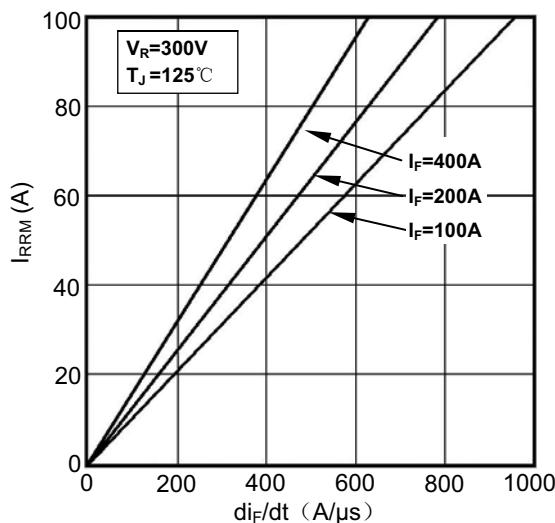


Figure 3. Reverse Recovery Current vs di_F/dt

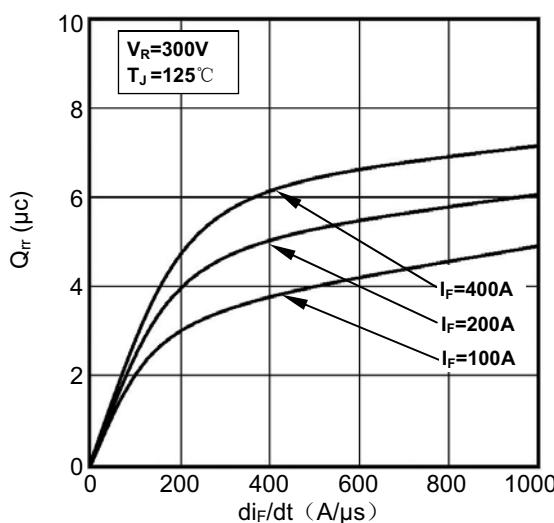


Figure 4. Reverse Recovery Charge vs di_F/dt

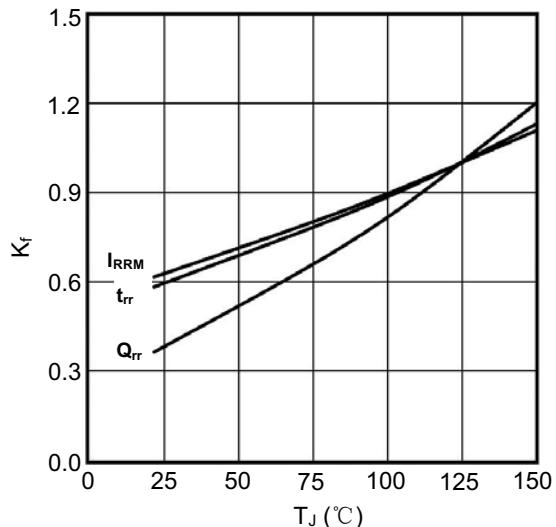


Figure 5. Dynamic Parameters vs Junction Temperature

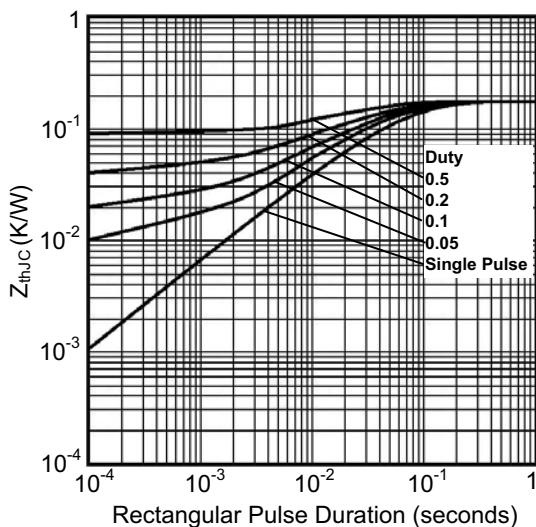


Figure 6. Transient Thermal Impedance

Package Outlines

